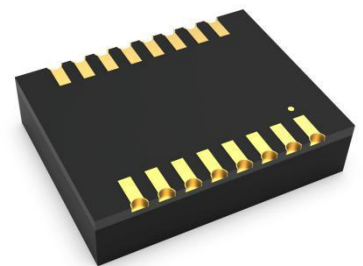


TD541S485H DFN package isolated RS485 Transceiver

Features

- Ultra-small, ultra-thin, chip scale DFN package
- Compliant with TIA/EIA-485-A standard
- Integrated isolated 5V power
- I/O power supply range supports 3.3V and 5V microprocessors(RXD can be directly connected when using 5V microprocessor; When using 3.3V microprocessor, please refer to point 5 in "Suggestions for Power Supply".)
- High isolation to 5000VDC
- Bus-Pin ESD protection up to 15kV(HBM)
- Baud rate up to 20Mbps
- >25kV/us CMTI
- Low communication delay
- 1/8 unit load—up to 256 nodes on a bus
- Bus fail-safe
- Bus driver short circuit protection
- Industrial operating ambient temperature range: -40℃ to +105℃
- Meet EN62368 standards
- Moisture Sensitivity Level (MSL) 3

Package



Applications

- Industrial Automation
- Building Automation
- Smart Electricity Meter
- Remote Signal Interaction, Transmission

Functional Description

TD541S485H is a half-duplex enhanced transceiver designed for RS-485 data bus networks, which is fully compliant with TIA/EIA-485-A standard and is suitable for data transmission of up to 20Mbps. Their logic side supports 3.3V and 5V logic level conversion. Receivers have an exceptionally high input impedance, which places only 1/8 of the standard load on a shared bus and up to 256 transceivers.

The reliability design of A and B pin is emphasized, including driver output over current protection and enhanced ESD design. The ESD protection level of A, B pin can be up to 15kV (Human Body Model).

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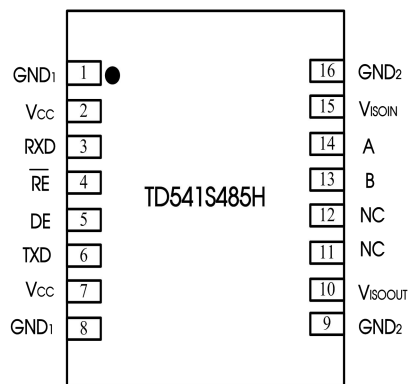
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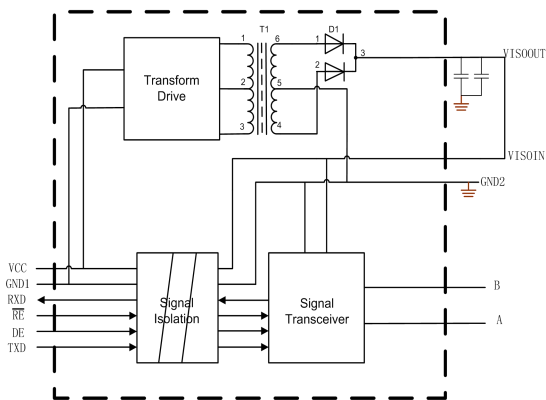
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Pin Connection



Note: All GND1 pins are internally connected.
All GND2 pins are internally connected.

Internal Block



Function Table

| Letter | Description |
|--------|----------------|
| H | High-Level |
| L | Low-Level |
| X | Unrelated |
| Z | High Impedance |

Table 1. Driver Function table

| TXD | DE | Output | |
|------|----|--------|---|
| | | A | B |
| H | H | H | L |
| L | H | L | H |
| X | L | Z | Z |
| Open | H | H | L |

Table 2. Receiver Function table

| Difference input $V_{ID} = (V_A - V_B)$ | \overline{RE} | RXD |
|--|-----------------|-------------|
| $-0.02\text{ V} \leq V_{ID}$ | L | H |
| $-0.22\text{ V} < V_{ID} < -0.02\text{ V}$ | L | Uncertainty |
| $V_{ID} \leq -0.22\text{ V}$ | L | L |
| Open circuit | L | H |
| Short circuit | L | H |

Pin Descriptions

| Pin Number | Pin Name | Pin Functions |
|------------|---------------------|--|
| 1 | GND ₁ | Ground(Logic side). |
| 2 | V _{CC} | Power supply. By using 0.1uF ceramic capacitance ground(GND1). |
| 3 | RXD | Receiver output pin. |
| 4 | \overline{RE} | Receiver enable input. When \overline{RE} is low, if $(A - B) \geq -20$ mV, then RXD = high. if $(A - B) \leq -220$ mV, then RXD = low. |
| 5 | DE | Driver enable input. When DE is high, outputs are enabled. When DE is low, outputs are high impedance. Drive DE low and \overline{RE} high to enter shutdown mode. |
| 6 | TXD | Driver input pin. |
| 7 | V _{CC} | Power supply. By using 1uF ceramic capacitance ground(GND1). |
| 8 | GND ₁ | Ground(Logic side). |
| 9 | GND ₂ | Ground (Bus Side). |
| 10 | V _{ISOOUT} | Insulation power output. By using 1uF Ceramic capacitance ground(GND2, pin9). The pin needs to be connected to pin15 in application. |
| 11 | NC | No Connect. |
| 12 | NC | No Connect. |
| 13 | B | RS485 Bus B Line. |
| 14 | A | RS485 Bus A Line. |
| 15 | V _{ISOIN} | Insulation power input. By using 0.1uF ceramic capacitance ground(GND2, pin16). The pin needs to be connected to pin10 in application. |
| 16 | GND ₂ | Ground (Bus Side). |

Absolute Maximum Ratings

General test conditions: Free-air, normal operating temperature range (Unless otherwise specified).

| Parameters | Unit |
|--|---|
| Supply voltage | -0.3V to +6V |
| A, B Bus voltage | -8V to +13V |
| Digital Input Voltage (DE, \overline{RE} , TXD, RXD) | -0.3V to +6V |
| Operating Temperature Range | -40°C to +105°C |
| Storage Temperature Range | -50°C to +125°C |
| Reflow Soldering Temperature | Peak temp. $\leq 250^{\circ}\text{C}$, maximum duration $\leq 60\text{s}$ at 217°C . Please also refer to IPC/JEDEC J-STD-020D. 3. |

Important: Exposure to absolute maximum rated conditions for an extended period may severely affect the device reliability, and stress levels exceeding the "Absolute Maximum Ratings" may result in permanent damage.

Recommended Operating Conditions

| Symbol | Recommended operating | Min. | Typ. | Max. | Unit |
|-----------------|---|----------|------|-----------------|--------------------|
| V _{CC} | Supply voltage | 4.75 | 5 | 5.25 | V |
| V _I | Voltage at any bus terminal (differential or common mode) | -7 | | 12 | |
| V _{IH} | High-level input voltage(TXD, DE, \overline{RE}) | 2 | | V _{CC} | |
| V _{IL} | Low-level input voltage(TXD, DE, \overline{RE}) | 0 | | 0.8 | |
| I _{OS} | Output current | Driver | | 60 | mA |
| | | Receiver | | 8 | |
| R _{IN} | Differential output load resistance | 54 | 60 | | Ω |
| T _A | Operating temperature range | -40 | | 105 | $^{\circ}\text{C}$ |
| - | Signaling rate | | | 20 | Mbps |

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit | |
|---|---|---|------------------------|-----------------------|-----------------------|------|-------|
| Driver | | | | | | | |
| V _{OD} | Differential driver output | No load | 3.5 | | | V | |
| | | R _L =54Ω, Figure 6 | 1.5 | 2.0 | | V | |
| | | R _L =100Ω, Figure 6 | 2.0 | | | | |
| ΔV _{OD} | Δ V _{OD} for complementary output states | R _L =54Ω, Figure 6 | | | ±0.2 | V | |
| V _{OC} | Common-Mode output voltage | Figure 5 | 1 | | 3 | V | |
| ΔV _{OC(SS)} | Δ V _{OC} for complementary output states | Figure 5 | -0.1 | | 0.1 | V | |
| I _{OS} | Output short-circuit current | -7V≤V _A or V _B ≤ +12V | | ±110 | ±250 | mA | |
| R _{TXD} | Internal TXD Pull up Resistor | | | 5.1 | | kΩ | |
| R _{DE} | Internal DE Pull down Resistor | | | 5.1 | | kΩ | |
| Receiver | | | | | | | |
| V _{IT(+)} | Positive differential input threshold voltage | -7 V ≤ V _A or V _B ≤ +12 V | | | -20 | mV | |
| V _{IT(-)} | Negative differential input threshold voltage | -7 V ≤ V _A or V _B ≤ +12 V | | -220 | | mV | |
| V _{hys} | Hysteresis voltage (V _{IT+} – V _{IT-}) | -7 V ≤ V _A or V _B ≤ +12 V | | 20 | | mV | |
| R _{ID} | Differential input resistance(A, B) | -7 V ≤ V _A or V _B ≤ +12 V | | 96 | | kΩ | |
| I _I | Input current (A, B) | DE=0, $\overline{\text{RE}}$ =0, V _{CC} =0 or 5V | V _{OUT} =12V | | 190 | 250 | uA |
| | | | V _{OUT} = -7V | -200 | -110 | | uA |
| V _{OH} | RXD output high voltage | I _{OUT} = 20 μA, V _A – V _B = 0.2 V | | V _{CC} – 0.1 | | V | |
| | | I _{OUT} = 4 mA, V _A – V _B = 0.2 V | | V _{CC} – 0.4 | V _{CC} – 0.2 | V | |
| V _{OL} | RXD output low voltage | I _{OUT} = -20 μA, V _A – V _B = -0.2 V | | | 0.1 | V | |
| | | I _{OUT} = -4 mA, V _A – V _B = -0.2 V | | | 0.4 | V | |
| Power supply and safeguard characteristic | | | | | | | |
| I _{CC} | Supply current | DE= $\overline{\text{RE}}$ =0V | | | 15 | 30 | mA |
| I _{CC} | Working current | Between A, B 100Ω load | | | 60 | 80 | mA |
| | | Between A, B 54Ω load, 1Mbps | | | 75 | 105 | mA |
| | | Between A, B 54Ω load, 20Mbps | | | | 120 | mA |
| ESD | HBM | A, B to GND | | | | ±15 | kV |
| | | Other pin | | | | ±2 | kV |
| EFT | IEC61000-4-4 | A, B and GND | | | | ±2 | kV |
| SURGE | IEC61000-4-5 | A, B and GND(Common Mode) | | | | ±2 | kV |
| VI-O | Insulate voltage | | | | | 5000 | VDC |
| | Insulate impedance | | | 1 | | | GΩ |
| | Insulate capacitance | | | | 3 | | pF |
| CMTI | Common mode transient immunity | TXD = V _{CC} or 0 V, V _{CM} = 1 kV, transient magnitude = 800 V | | 25 | | | kV/us |

Transmission Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---|---|---|------|------|------|------|
| - | Maximum data rate | Duty 40% ~ 60% | | | 20 | Mbps |
| Test conditions: 25°C, transmission rate = 1Mbps | | | | | | |
| T_{PHL}, T_{PLH} | Driver propagation delay | $R_L = 54\Omega, C_L = 50pF$, Figure 7 | | 100 | 200 | ns |
| $ T_{PHL} - T_{PLH} $ | Driver skew ($ T_{PHL} - T_{PLH} $) | | | 30 | 100 | ns |
| T_R, T_F | Driver rise/fall time | | 30 | 50 | 100 | ns |
| T_{PHL}, T_{PLH} | Receiver propagation delay | $C_L = 15pF$, Figure 8 | | 50 | 150 | ns |
| $ T_{PHL} - T_{PLH} $ | Receiver skew ($ T_{PLH} - T_{PHL} $) | | | 15 | 50 | ns |
| T_R, T_F | Receiver rise/fall time | $C_L = 15pF$, Figure 8 | | 15 | | ns |
| Test conditions: 25°C, transmission rate = 20Mbps | | | | | | |
| T_{PHL}, T_{PLH} | Driver propagation delay | $R_L = 54\Omega, C_L = 50pF$, Figure 7 | | | 140 | ns |
| $ T_{PHL} - T_{PLH} $ | Driver skew ($ T_{PHL} - T_{PLH} $) | | | | 15 | ns |
| T_R, T_F | Driver rise/fall time | | | | 50 | ns |
| T_{PHL}, T_{PLH} | Receiver propagation delay | $C_L = 15pF$, Figure 8 | | 60 | 150 | ns |
| $ T_{PHL} - T_{PLH} $ | Receiver skew ($ T_{PLH} - T_{PHL} $) | | | | 20 | ns |
| T_R, T_F | Receiver rise/fall time | $C_L = 15pF$, Figure 8 | | 25 | | ns |

Physical Specifications

| Parameters | Value | Unit |
|------------|------------|------|
| Weight | 0.9(Typ.) | g |

Typical Performance Curves

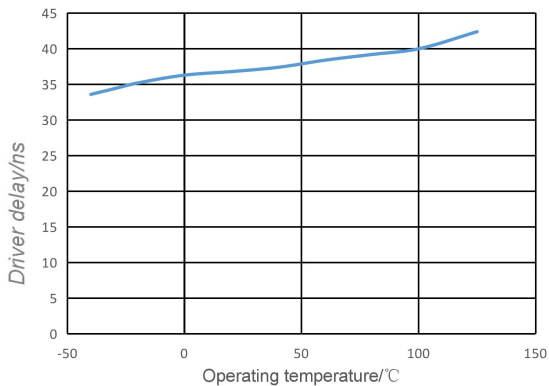


Figure 1. Driver delay vs. Operating temperature

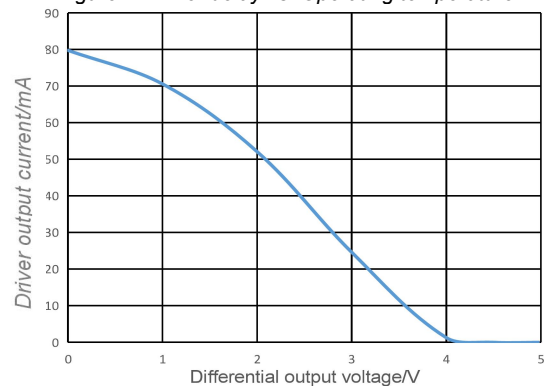


Figure 3. Driver output current vs. Differential output voltage

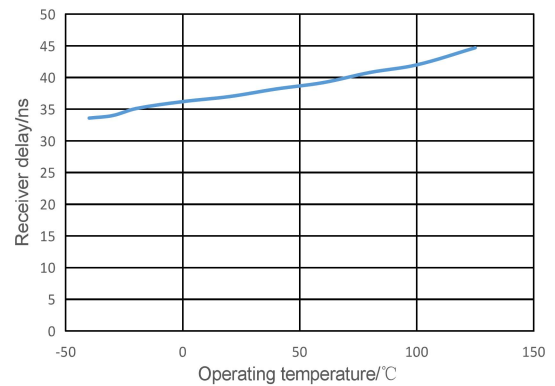


Figure 2. Receiver delay vs. Operating temperature

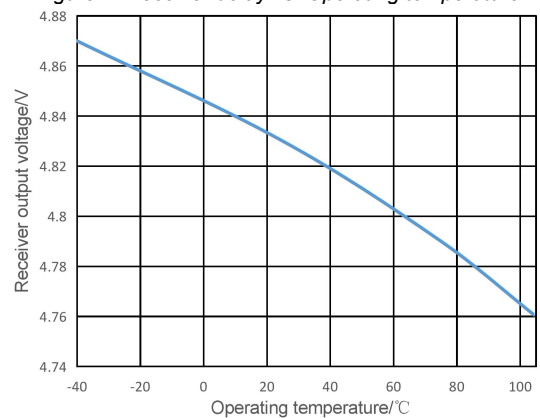


Figure 4. Receiver output high voltage vs. Operating temperature

Test Circuits

Note: Test condition load capacitance includes test probe and fixture parasitic capacitance (no special instructions). The rising and falling edges of the test < 6ns. frequency 100kHz. duty50%. resistance $Z_O = 54\Omega$.

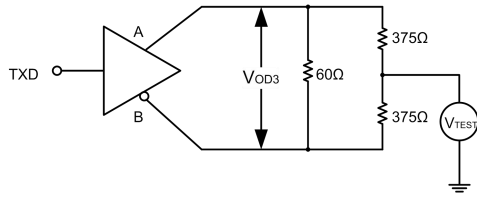


Figure 5. Common mode output test circuit

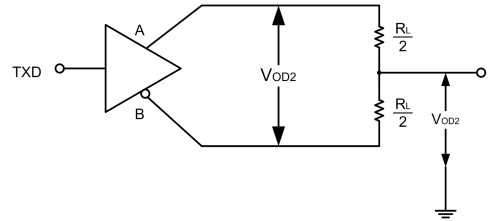


Figure 6. Differential output test circuit

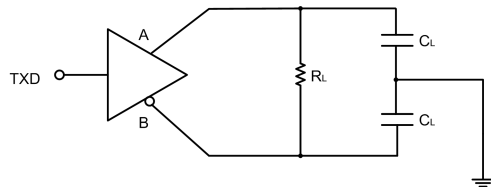


Figure 7. Drive propagation delay test circuit and wave forms

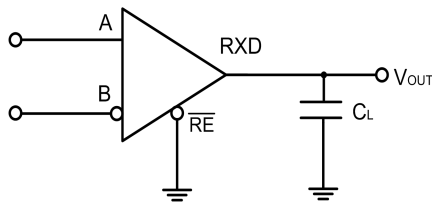


Figure 8. Receiver propagation delay test circuit and wave forms

Detailed Description

TD541S485H is a semi-duplex enhanced RS485 isolated transceiver with isolated power supply. In addition to an isolated power supply, each transceiver contains a drive and a receiver. The transceiver has a standby bus failure protection function to ensure that the receiver output is high when the receiver input is open, short, or when the bus is idle. TD541S485H adopts 5VDC single power supply. The whole machine can monitor the overall working state of the module and limit the output high current, so as to prevent the bus overload or short circuit from causing non-recoverable damage to the transceiver.

Receiver input filter: TD541S485H receiver integrated high performance input filter, the filter can greatly enhance the receiver's noise suppression ability to high speed differential signal. Therefore, the transmission delay of the receiver is also caused by this reason.

Bus failure protection: In general, when $-220\text{mV} < A - B < -20\text{mV}$, the bus receiver will be in an indeterminate state. This phenomenon occurs when the bus is idle. Bus failure protection ensures that the receiver outputs a high level when the receiver input is open, short, or when the bus access port matches the resistance. TD541S485H receiver threshold voltage is relatively accurate, and the threshold voltage to the reference ground has a margin of at least 10mV, which can ensure that even if the bus differential voltage is 0V, the receiver output level is high, and meets the requirements of EIA/TIA-485 standard $\pm 200\text{mV}$.

The bus load capacity (256 point): standard RS485 receiver input impedance is defined as 12 k Ω (unit load). A standard RS485 driver can drive at least 32 load units. TD541S485H bus receiver designed by 1/8 unit load, the input impedance is greater than 96 k Ω . As a result, the bus allows access to more transceivers (up to 256). TD541S485H can also be mixed with the standard RS485 transceiver with 32 unit loads (cumulative receiver load cannot exceed 32 units).

Low power SHUTDOWN mode: When high level is input and low power is input, the transceiver enters SHUTDOWN mode. When the transceiver enters off mode, its overall standby power consumption decreases, DE can be short-connected and controlled by the same I/O. If the high level is input and the holding time of DE low level is less than 50ns, the transceiver cannot enter the off mode. If the holding time can be maintained at least 600ns, the transceiver will reliably enter the off mode.

Drive output protection: TD541S485H internal integrated drive short circuit (or overcurrent) protection module. In case of bus error or driver short circuit, the module can limit the output current of the driver within a certain limit.

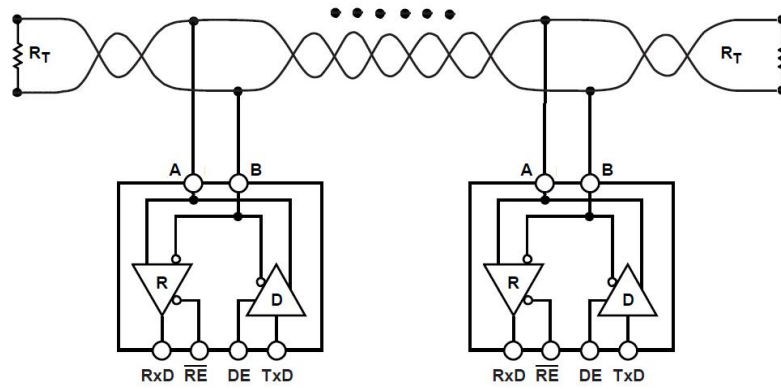


Figure 9. Typical application circuit (Half-Duplex Network Topology)

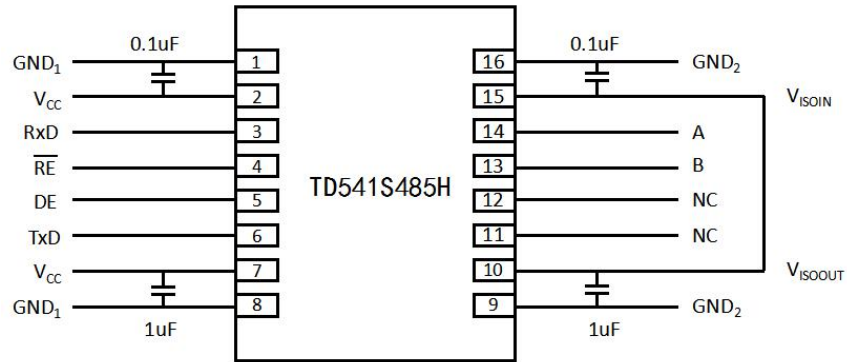


Figure 10. Type PCB layout

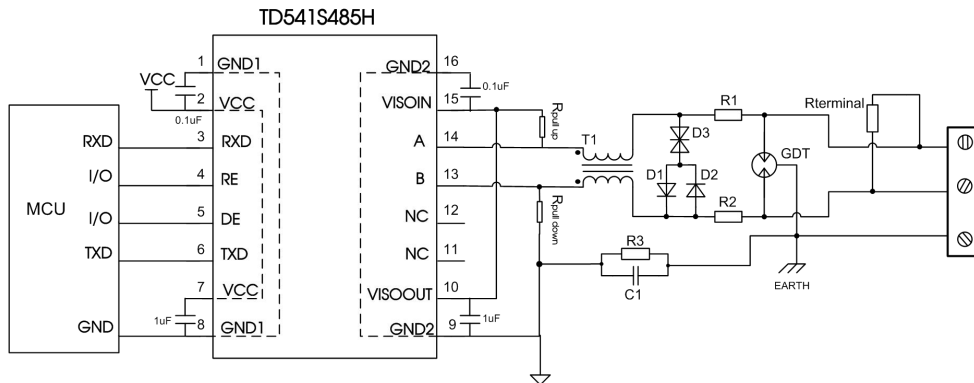


Figure 11. Port protection circuit for harsh environments

Recommended components and values:

| Component | Recommended part, value | Component | Recommended part, value |
|-----------|-------------------------|-----------------------|-------------------------|
| R3 | 1MΩ | R1, R2 | 2.7Ω/2W |
| C1 | 1nF, 2kV | D1, D2 | 1N4007 |
| T1 | ACM2520-301-2P | D3 | SMBJ8.5CA |
| GDT | B3D090L | R _{terminal} | 120Ω |

As the modules internal A / B lines come with its own ESD protection, which generally satisfy most application environments without the need for additional ESD protection devices. For harsh and noisy application environments such as motors, high voltage/current switches, lightning and similar however, we recommended that the user protects the module' s A / B lines with additional measures and external components such as TVS tube, common mode inductors, Gas discharge tube, shielded twisted pair of wires with the same single network Earth point. Figure 11 shows our recommended circuit diagram for such type of applications with components and values given in the table above. This recommendation is for reference only and may have to be adapted accordingly with appropriate component values in order to match the actual situation and application.

Note: Select the R_{terminal} according to the actual application.

- ① Power isolation V_{ISOOUT} need through a series of capacitors connected to the output pin V_{ISOIN} , in addition to the mentioned in article 4 of the pull up and down function, the power supply is not recommended for other purposes, otherwise it may cause the bus voltage did not meet the requirements of communication, causes the communication failure.
- ② DE and \overline{RE} pin do not support dangling. If the pin is not access controller, the recommended by 30 k Ω pulldown resistor pins connect to GND. Keep the node in the receiving state only, not affect the bus.
- ③ DE, \overline{RE} , TXD pin is always not allow to set to open drain output state connect the controller, otherwise it will lead to uncertain consequences.
- ④ To maintain A - B bus idle stability, we need at least one node will pull up A to V_{ISOIN} and drop down B to GND₂ on the bus. Overall network at the same time pull up and drop down resistance of the parallel value must around 380 Ω to 420 Ω (0.2W).

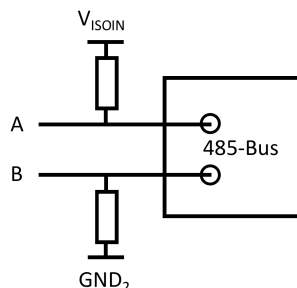


Figure 12. Typical connection of pull-up and pull-down

- ⑤ The output of TD541S485H to RXD is only compatible with 5V system, if the I/O port is 3.3V level and does not support 5V input, please refer to the following recommended circuit :

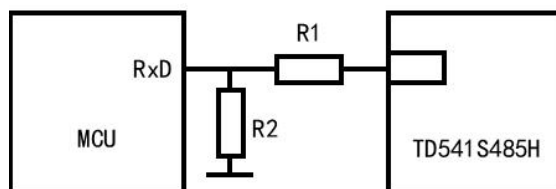


Figure 13. Match MCU system connection

The calculation formula of resistance partial voltage of conventional step-down-circuit is

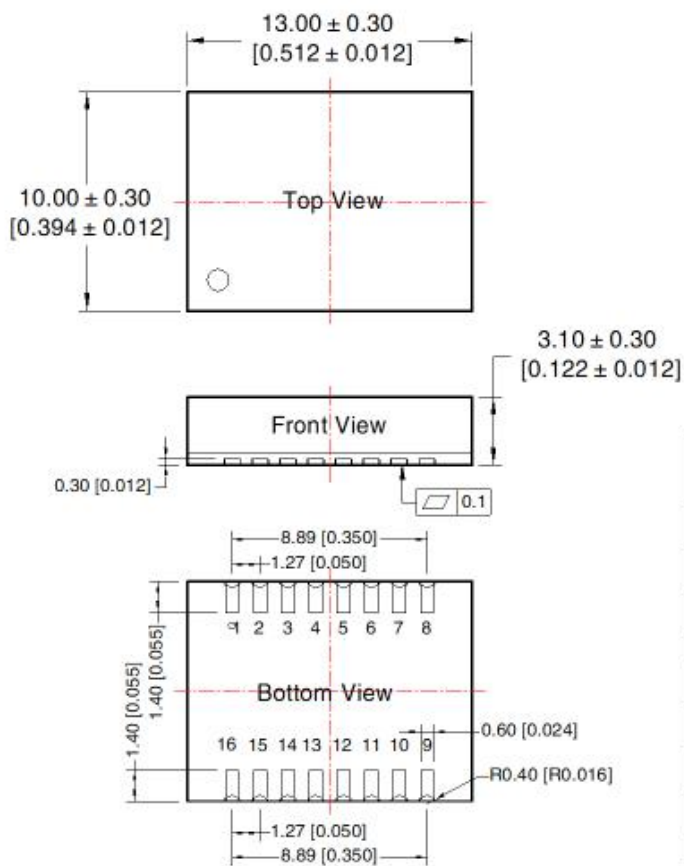
$$R1 = \frac{V_{out} - V_{in}}{V_{in}} R2$$

Where R1,R2 is piezoelectric resistance value of the connected part, V_{out} is TD541S485H output voltage, V_{in} is MCU RXD input voltage. The recommended value is R1=1k Ω , R2=2k Ω .

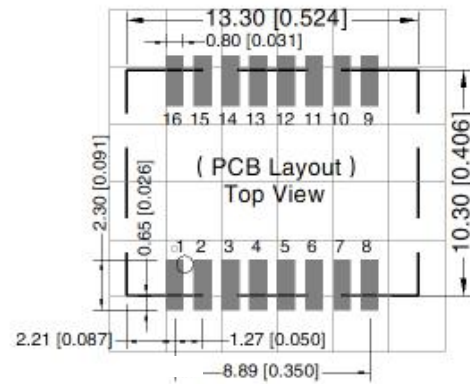
- ⑥ Hot-swap is not supported.
- ⑦ If the external input of TXD is insufficient, the pull-up resistor should be added according to the situation.
- ⑧ Refer to IPC 7093 for the welding process design of this product. For detailed operation guidance, please refer to *Hot Air Gun Welding Operation Instruction for DFN Package Product* or *Welding Operation Instruction for DFN Package Product*.

Ordering Information

| Part number | Package | Number of pins | Product marking | Tape & Reel |
|-------------|---------|----------------|-----------------|-------------|
| TD541S485H | DFN | 16 | TD541S485H | 300/REEL |

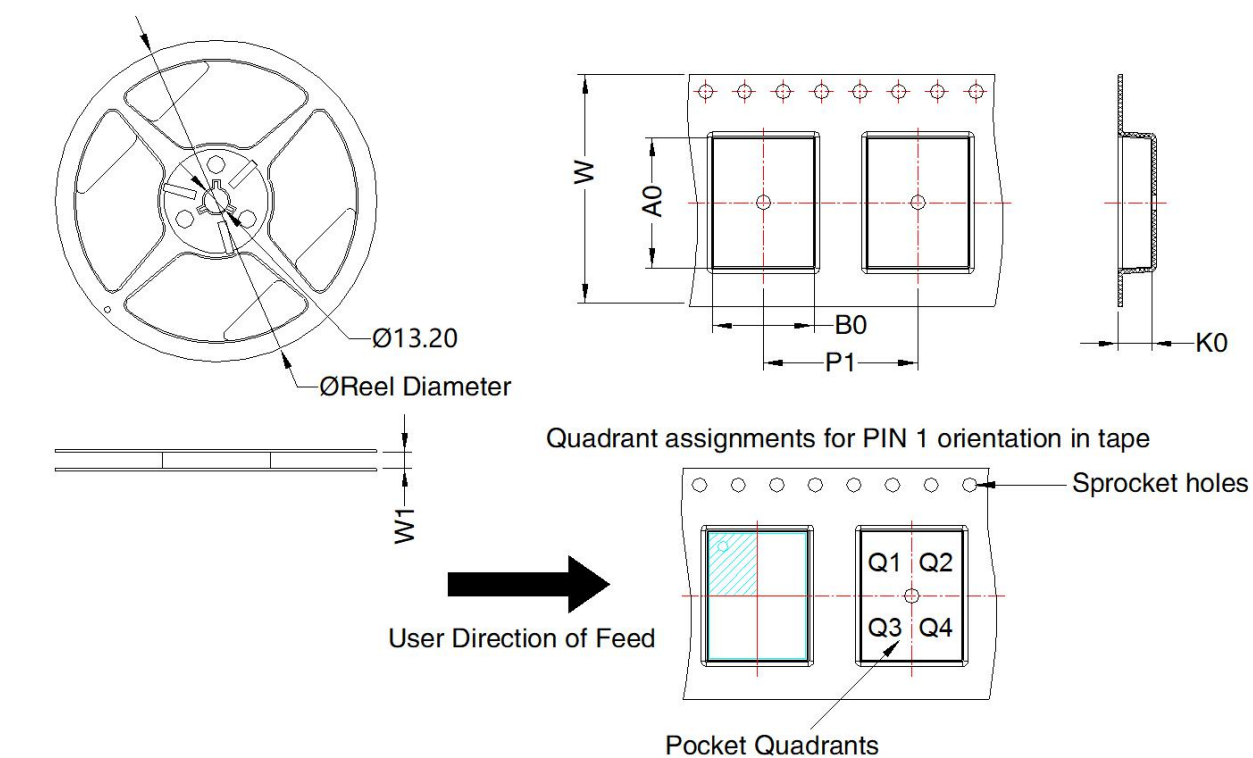


Note:
Unit: mm[inch]
General tolerances: ± 0.10 [± 0.004]



Note: Grid 2.54*2.54mm

| Pin-Out | | | |
|---------|------|-----|---------|
| Pin | Mark | Pin | Mark |
| 1 | GND1 | 9 | GND2 |
| 2 | VCC | 10 | VISOOUT |
| 3 | RXD | 11 | NC |
| 4 | RE | 12 | NC |
| 5 | DE | 13 | B |
| 6 | TXD | 14 | A |
| 7 | VCC | 15 | VISOIN |
| 8 | GND1 | 16 | GND2 |



| Device | Package Type | Pin | MPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------|--------------|-----|-----|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TD541S485H | DFN 10x13 | 16 | 300 | 180.0 | 24.4 | 13.52 | 10.52 | 3.5 | 16.0 | 24.0 | Q1 |

MORNSUN Guangzhou Science & Technology Co., Ltd.

Address: No. 8 Nanyun 4th Road, Huangpu District, Guangzhou, China

Tel: 86-20-38601850

Fax: 86-20-38601272

E-mail: info@mornsun.cn

www.mornsun-power.com